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PATENT
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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of :
Khandros et al.
Serial No. 08/030,194 :
Filed: April 28, 1993 :
For: SEMICONDUCTOR CHIP
ASSEMBLIES, METHODS OF
MAKING SAME AND COMPONENTS:
FOR SAME :
X

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Examiner:

Date: July 27, 1993

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Hon. Commissioner of Patents
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Washington, D.C. 20231

INFORMATION DISCLOSURE STATEMENT

Sir:

It is respectfully requested that the references listed on the enclosed Form PTO-1449 be made of record and considered with respect to the above-referenced U.S. Patent application. A copy of each reference is enclosed. Submission of the present Information Disclosure Statement should not be taken as an admission that the same are pertinent or material.

Respectfully submitted,

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